

74AUP1T34

(Top View)

6

A 2 5 NC

X2-DFN1410-6

VCCB

1

GND 3 4 Y

SINGLE-BIT DUAL POWER SUPPLY TRANSLATING BUFFER WITH 3 STATE OUTPUTS

5 VCCB VCCA

4 Y

(Top View)

1 6

2 5

X2-DFN1010-6

GND 3 4

Vccb

NC

Y

Description

The 74AUP1T34 is a single-bit, dual-supply, noninverting buffer translator suitable for transmitting a single logic bit across different voltage domains. It is a unidirectional translator from A to Y. The input pin A has input switching thresholds related to V_{CCA}, operating from 0.9V to 3.6V. The output pin Y has a HIGH level output voltage that tracks V_{CCB}, also operating from 0.9V to 3.6V. This arrangement allows for universal low-voltage translation between any voltages from 0.9V to 3.6V.

The three-state feature occurs when the V_{CCA} power-supply voltages are zero. This is also an I_{OFF} feature and allows the output to remain in a high-impedance state, preventing damaging backflow currents and providing power-down electrical isolation of up to 3.6V. If the V_{CCB} is at ground, the input circuits at pin A are disabled and no input current flows regardless of any applied voltage between 0V and 3.6V.

The 74AUP1T34 is available in the SOT353, X2-DFN1410-6, and X2-DFN1010-6 packages, and is specified for operation from -40°C to +125°C among all supply voltages. The wide temperature ranges and high ESD tolerance facilitate their use in harsh applications.

Features

- Wide Supply Voltage Range:
 - V_{CC}(A): from 0.9V to 3.6V
 - V_{CC}(B): from 0.9V to 3.6V
- ±6mA Output Drive at 3V
- Low-Static Power Consumption; Icc = 5µA (Maximum)
- High Noise Immunity (100mV Hysteresis Typical)
- IOFF Supports Partial Power-Down Mode Operation
- IOFF Controlled by VCCB Being at 0V
- Input Isolation when V_{CCA} is Ground; No Input Current Even when Floating
- ESD Protection Exceeds JESD 22
 - Exceeds 5000V Human Body Model (A114)
 - Exceeds 1000V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, class II
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- An automotive-compliant part is available under separate datasheet (74AUP1T34Q)

Applications

Voltage level translation:

Pin Assignments

VCCA 1

A 2

GND 3

(Top View)

SOT353

VCCA

- Well suited to join logic types operating at different voltages
- Power-down signal isolation:
 - When V_{CCA} = GND output is three-state
 - When V_{CCB} = GND input is disabled and may be left floating
- Wide array of products such as:
- Cell phones, tablets, e-readers
- PCs, notebooks, netbooks, ultrabooks
- Networking, routers, gateways
- Personal electronics
- Telecommunications
- Industrial devices

- Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>



Pin Descriptions

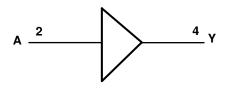
Pin Name	Pin SOT353	Pin X2-DFN1410-6	Pin X2-DFN1010-6	Function
Vcca	1	1	1	Supply for pin A
А	2	2	2	Data Input (threshold based on V _{CCA})
GND	3	3	3	Ground
Y	4	4	4	Data Output (VOH based on VCCB)
NC		5	5	NC (can be connected to any potential)
VCCB	5	6	6	Supply for pin Y

Function Table

Supply V	Supply Voltage		
VCCA	Vccb	Α	Y
0.9V to 3.6V	0.9V to 3.6V	L	L
0.9V to 3.6V	0.9V to 3.6V	Н	Н
0V	0.9V to 3.6V	Х	Z
0V to 3.6V	0V	Isolated (Note 4)	Z

Note: 4. Floating input pin is allowed for this case

Logic Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.) (Note 5)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	5	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
Vcca, Vccb	Supply Voltage Range	-0.3 to +4.0	V
VI	Input Voltage Range	-0.5 to +4.6	V
Vo	Voltage Applied to Output in High-Impedance or IOFF State	-0.5 to +4.6	V
Vo	Voltage Applied to Output in High or Low State	-0.5 to +4.6	V
Ік	Input Clamp Current VI < 0	-50	mA
loк	Output Clamp Current	-50	mA
lo	Continuous Output Current	±50	mA
_	Continuous Current Through V _{CCA} or GND	±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
Tstg	Storage Temperature	-65 to +150	°C

Note: 5. Stresses beyond the absolute maximum can result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Condition (@TA = +25°C, unless otherwise specified.) (Note 6)

Symbol	Parameter	Vcca	Vссв	Min	Max	Units
VCCA	Operating Voltage	—	—	0.9	3.6	V
V _{CCB}	Operating Voltage	—	_	0.9	3.6	V
		0.9V to 1.95V	0.9V to 3.6V	0.65 x Vcca	—	
VIH High-Level Input Voltage	High-Level Input Voltage	2.3V to 2.7V	0.9V to 3.6V	1.6	—	V
		3V to 3.6V	0.9V to 3.6V	2	—	
		0.9V	0.9V to 3.6V	—	0.3 x Vcca	
VIL	Low-Level Input Voltage	1V to 1.95V	0.9V to 3.6V	—	0.35 x Vcca	V
VIL		0.35 x Vcca	0.9V to 3.6V	—	0.7	v
		3V to 3.6V	0.9V to 3.6V	—	0.8	1
TA	Operating Free-Air Temperatu	re		-40	+125	°C

Note:

te: 6. Test condition for each of the three package types: Device mounted on JEDEC standard PCB per JESD51, with minimum recommended pad layout.

Electrical Characteristics (@TA = -40°C to +125°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions		Vcca	VCCB	TA = -40°C	to +125°C	Unit
Symbol	Parameter		est conditions	VCCA	VCCB	Min	Max	Unit
		Іон = -	100µA	0.9V to 3.6V	0.9V to 3.6V	V _{ССВ} – 0.2	_	
		Юн = -	0.25mA	0.9V to 1V	0.9V to 1V	0.75 х Vссв	_	
	High-Level Output	Іон = -	1.5mA	1.2V	1.2V	1	_	v
Voh	Voltage	Юн = -	2mA	1.65V	1.65V	1.32	_	v
		Іон = -	3mA	2.3V	2.3V	1.9	_	
		Юн = -	6mA	3V	3V	2.72	_	
		$I_{OL} = 1$	00µA	0.9V to 3.6V	0.9V to 3.6V	_	0.1	
		$I_{OL} = 0$.25mA	0.9V to 1V	0.9V to 1V	_	0.1	
	Low-Level Output	$I_{OL} = 1$.5mA	1.2V	1.2V	_	0.3 x V _{CCB}	
Vol	Voltage	$I_{OL} = 2mA$		1.65V	1.65V	_	0.31	V
	_		I _{OL} = 3mA		2.3V	_	0.31	1
		IoL = 6	mA	3V	3V	_	0.31	
lı	Input Current	$V_I = V_C$	CA or GND	0.9V to 3.6V	0.9V to 3.6V	_	±1	μA
1	Off-State Current	A pin		0V	0 to 3.6V	_	±5	
IOFF	On-State Current	Y pin	V_1 or $V_0 = 0V$ to 3.6V	0 to 3.6V	0V	—	±5	μA
				0.9V to 3.6V	0.9V to 3.6V	_	5	
ICCA	Supply Current	VI = Vc	CA OF GND	0.9V to 3.6V	VCCA	—	2	μA
ICCA	Io = 0mA		۱A	0V	0V to 3.6V		1	μΛ
				0.9V to 3.6V	0V	—	1	
				0.9V to 3.6V	0.9V to 3.6V	—	5	
Іссв	Supply Current	$V_I = V_C$	CA or GND	0.9V to 3.6V	VCCA	_	2	μA
ICCB	Cupply Current	$l_0 = 0n$	A	0V	0V to 3.6V	_	1	μ/ (
				0.9V to 3.6V	0V	—	1	
ICCA + ICCB	Supply Current	$V_1 = V_0$ $I_0 = 0m$	cca or GND nA	1.2V to 3.6V	1.2V to 3.6V	—	20	μA
Cı	Input Capacitance	A pin	VI = 3.3V or GND	3.3V	3.3V	_	4	pF
Co	Output Capacitance	Y pin	$V_{O} = 3.3V$ or GND	0V	3.3V	_	7	pF

Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Тур	Max	Unit
	θ _{JA} Thermal Resistance Junction-to-Ambient	SOT353		—	318	—	
θ _{JA}		X2-DFN1410-6	Note 7	_	210	_	°C/W
		X2-DFN1010-6			180	_	
	Thermal Resistance	SOT353	Note 7	—	156	_	
θJC		X2-DFN1410-6			54	_	°C/W
	Junction-to-Case	X2-DFN1010-6		—	34	_	

Note: 7. Test condition for each of the three package types: Device mounted on JEDEC standard PCB per JESD51, with minimum recommended pad layout.



Switching Characteristics

Parameter	Test Conditions	VCCA	Vссв	Min	Тур	Max	Units
			0.9V	_	25		
			1.2V	—	18	—	
	$C_L = 5pF$	0.9V	1.65V	_	16.2		
			2.3V	—	16.3	—	
			3V		16.8	—	
			0.9V	—	—	42.5	
			1.2V	—	—	24.9	
	$C_L = 5pF$	1.2V	1.65V	—	—	23.2	
			2.3V	—	_	22.6	
			3V	—	—	22.5	
			0.9V	—		40	
tplh/tphl			1.2V	_	—	10.7	
Propagation Delay Time	$C_L = 5pF$	1.65V	1.65V			8.84	ns
Low-to-High Output / High-to-Low Output			2.3V			8.08	
			3V	_	_	7.88	
			0.9V	_	_	41.3	
			1.2V	_	_	8.02	
	$C_L = 5pF$	2.3V	1.65V	_		5.73	
	- L		2.3V		_	4.92	
			3V		_	4.2	
	CL = 5pF	3V	0.9V			42.5	-
			1.2V		_	7.61	
			1.65V	_	_	5.5	
			2.3V			4.65	
			3V		_	4.39	
			0.9V		28.9	4.39	
		-	1.2V		19.8		
	CL = 10pF	0.9V	1.65V		17.9		
	OL = TOPF	0.90	2.3V		18		
		-	3V		18.5	—	
					-		
		–	0.9V		—	43.22	
	0 10 5	1.01/	1.2V		—	12.33	
	CL = 10pF	1.2V	1.65V	—	—	9.57	
		-	2.3V		—	8.81	-
			3V	—	—	8.61	
tplh/tphl		_	0.9V		—	40.44	
Propagation Delay Time	0 10 5	4.051/	1.2V	—	—	9.21	
Low-to-High Output /	$C_L = 10 pF$	1.65V	1.65V		—	6.57	ns
High-to-Low Output		_	2.3V		—	5.5	
			3V			4.73	
		_	0.9V		—	41.56	
			1.2V	—	—	8.3	
	$C_L = 10 pF$	2.3V	1.65V	—	—	5.54	
			2.3V		_	4.42]
			3V	_	—	4.01	
			0.9V	—	—	42.81	
		[1.2V	—	—	7.87	
	$C_L = 10 pF$	3V	1.65V		—	4.55	-
			2.3V	_	—	3.8	
			3V			3.36	



Switching Characteristics (continued)

							Units
			0.9V	—	30.6	—	
		Γ	1.2V	—	21.6	—	
	CL = 15pF	0.9V	1.65V	—	19.6	—	
			2.3V	—	19.7	—	
			3V	—	20.3		
			0.9V	—		43.87	
			1.2V	—	_	12.9	
	C _L = 15pF	1.2V	1.65V	—		10.3	
			2.3V	_		9.54	
			3V	_	—	9.34	
			0.9V	_	_	40.78	
tplh/tphl			1.2V	_	_	9.59	
Propagation Delay Time	$C_L = 15 pF$	1.65V	1.65V	_		6.95	ns
Low-to-High Output / High-to-Low Output			2.3V	_	_	5.87	
			3V		_	5.07	
			0.9V	_	_	41.79	
		-	1.2V	_	_	8.55	
	C∟ = 15pF	2.3V	1.65V			5.8	
	OL = 15pi	2.50	2.3V			4.68	
		–	3V			4.00	
			0.9V	—		43.09	
	C _L = 15pF	3V		—	—		
			1.2V	—	—	8.16	
			1.65V	—	_	4.84	
			2.3V	—	—	4.09	
			3V	—	-	3.65	
		-	0.9V		32.1	—	-
		-	1.2V	—	21.3		
	$C_L = 30 pF$	0.9V	1.65V	—	18.7		
			2.3V	—	18	—	
			ЗV	—	18.3	—	
			0.9V	—	—	45.65	
			1.2V	—	—	14.76	
	$C_L = 30 pF$	1.2V	1.65V	—	—	12.37	
			2.3V	—		11.61	
			3V	—		11.41	
			0.9V	—		41.72	
tPLH/tPHL		Γ	1.2V	—	_	10.65	
Propagation Delay Time Low-to-High Output /	CL = 30pF	1.65V	1.65V	—	—	8.01	ns
High-to-Low Output			2.3V	—		6.94	
			3V	—		5.99	
			0.9V	_	—	42.44	
			1.2V	—	_	9.26	
	$C_L = 30 pF$	2.3V	1.65V	_	_	6.51	
			2.3V	_	_	6.39	
			3V		_	5.97	
			0.9V	_		43.69	
		-	1.2V	_	_	8.8	
	CL = 30pF	3V	1.65V	_		6.48	
	0L = 00pi		2.3V			5.72	
		-	3V			5.28	



Parameter Measurement Information (Notes B, C)

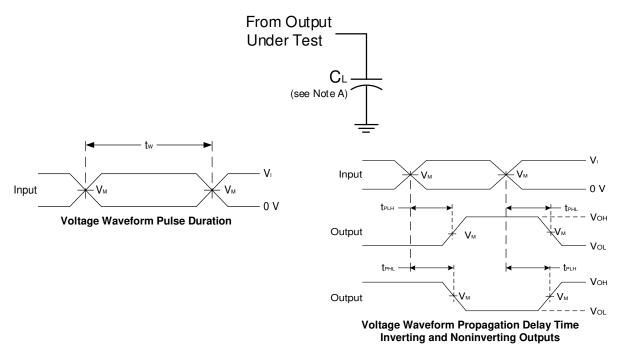
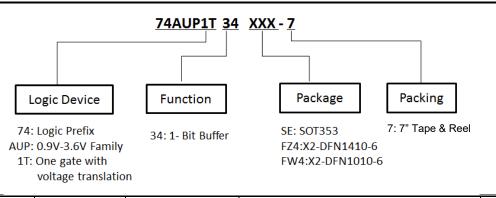


Figure 1. Load Circuit and Voltage Waveforms

- Notes: A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate \leqslant 10MHz.
 - C. t_{PLH} and t_{PHL} are the same as t_{PD} .



Ordering Information (Note 8)

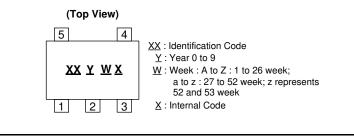


			Pa	cking	
Part Number	Package Code	Package	Qty.	Carrier	Part Number Suffix
74AUP1T34SE-7	SE	SOT353	3000	7" Tape & Reel	-7
74AUP1T34FZ4-7	FZ4	X2-DFN1410-6	5000	7" Tape & Reel	-7
74AUP1T34FW4-7	FW4	X2-DFN1010-6	5000	7" Tape & Reel	-7

Note: 8. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

(1) SOT353



Part Number	Package	Identification Code
74AUP1T34SE-7	SOT353	4S

(2) DFN Packages

(Top View)

$\begin{bmatrix} \underline{X} \underline{X} \\ \underline{Y} \underline{W} \underline{X} \end{bmatrix}$	XX : Identification Code Y : Year : 0~9 W : Week : A~Z : 1~26 week; a~z : 27~52 week; z represents 52 and 53 week
	<u>X</u> : Internal Code

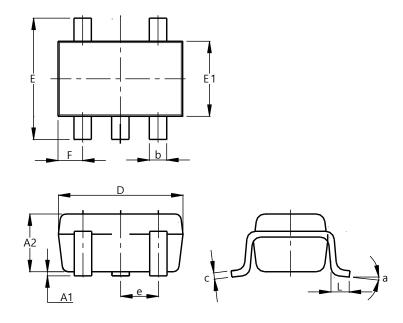
Part Number	Package	Identification Code		
74AUP1T34FZ4-7	X2-DFN1410-6	4S		
74AUP1T34FW4-7	X2-DFN1010-6	4U		



Package Outline Dimensions

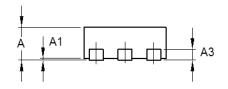
Please see http://www.diodes.com/package-outlines.html for the latest version.

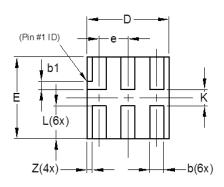
(1) Package Type: SOT353



SOT353			
Dim	Min	Max	Тур
A 1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
С	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
е	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
а	0°	8°	
All Dimensions in mm			

(2) Package Type: X2-DFN1010-6





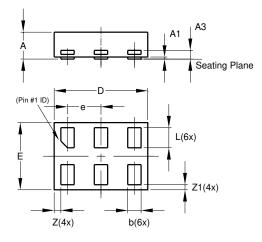
X2-DFN1010-6			
Dim	Min	Max	Тур
Α	—	0.40	0.39
A1	0.00	0.05	0.02
A3			0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
Е	0.95	1.05	1.00
е	—	_	0.35
L	0.35	0.45	0.40
Κ	0.15		_
Z		_	0.065
All Dimensions in mm			



Package Outline Dimensions (continued)

Please see http://www.diodes.com/package-outlines.html for the latest version.

(3) Package Type: X2-DFN1410-6



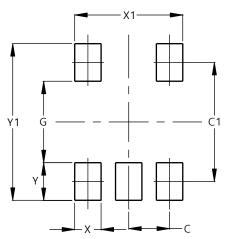
X2-DFN1410-6				
Dim	Min	Max	Тур	
Α		0.40	0.39	
A1	0.00	0.05	0.02	
A3			0.13	
b	0.15	0.25	0.20	
D	1.35	1.45	1.40	
E	0.95	1.05	1.00	
е			0.50	
L	0.25	0.35	0.30	
Z	_		0.10	
Z1	0.045	0.105	0.075	
All Dimensions in mm				



Suggested Pad Layout

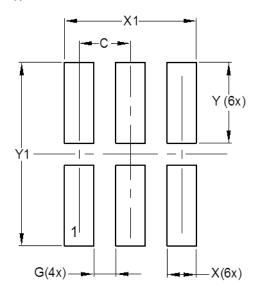
Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: SOT353



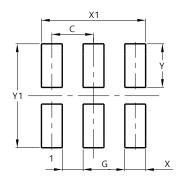
Dimensions	Value (in mm)
С	0.650
C1	1.900
G	1.300
Х	0.420
X1	1.720
Y	0.600
Y1	2.500

(2) Package Type: X2-DFN1010-6



Dimensions	Value (in mm)
С	0.350
G	0.150
Х	0.200
X1	0.900
Y	0.550
Y1	1.250

(3) Package Type: X2-DFN1410-6



Dimensions	Value (in mm)
С	0.500
G	0.250
Х	0.250
X1	1.250
Y	0.525
Y1	1.250



Mechanical Data

SOT353

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Mate Tin Plated Leads, Solderable per MIL-STD-202, Method 208 🕄
- Weight: 0.006 grams (Approximate)

X2-DFN1010-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 @
- Weight 0.0012 grams (Approximate)

X2-DFN1410-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 🐵
- Weight: 0.002 grams (Approximate)



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